	Hits	Search Text	DBs
1	1	("20040169444").PN.	US-PGPUB; USPAT; USOCR
2	13871	surface adj acoustic adj wave	EPO; JPO; DERWENT; IBM_TDB
3	117953	resin adj (film or layer)	EPO; JPO; DERWENT; IBM_TDB
4	1137874	dice\$1 or dicing or cut\$4 or split\$4	EPO; JPO; DERWENT; IBM_TDB
5	7	S2 and S3 and S4	EPO; JPO; DERWENT; IBM_TDB
6	103	S2 and S3	EPO; JPO; DERWENT; IBM_TDB
7	157725	saw or piezoelectric	EPO; JPO; DERWENT; IBM_TDB
8	129	S3 and S7 and S4	EPO; JPO; DERWENT; IBM_TDB
9	123	S8 not S6	EPO; JPO; DERWENT; IBM_TDB
10	2664119	resin or film	EPO; JPO; DERWENT; IBM_TDB
11	347	S2 and S4 and S10	EPO; JPO; DERWENT; IBM_TDB
12	965613	roll or roller	EPO; JPO; DERWENT; IBM_TDB
13	1	S11 and S12	EPO; JPO; DERWENT; IBM_TDB
14	340	S11 not S6	EPO; JPO; DERWENT; IBM_TDB
15	53	S2 and S12	EPO; JPO; DERWENT; IBM_TDB
16	9496	flip adj chip	EPO; JPO; DERWENT; IBM_TDB
17	8	S16 and S10 and S12	EPO; JPO; DERWENT; IBM_TDB

	Hits	Search Text	DBs
18	2	"2001332654"	EPO; JPO; DERWENT; IBM_TDB
19	2	"07176565"	EPO; JPO; DERWENT; IBM_TDB
20	3	"2002232260"	EPO; JPO; DERWENT; IBM_TDB
21	2	"2002198403"	EPO; JPO; DERWENT; IBM_TDB
22	2	"2000091381"	EPO; JPO; DERWENT; IBM_TDB
23	3	"2003283295"	EPO; JPO; DERWENT; IBM_TDB
24	1	"2002504773"	EPO; JPO; DERWENT; IBM_TDB
25	1	"97002596"	EPO; JPO; DERWENT; IBM_TDB
26	4	"972596"	EPO; JPO; DERWENT; IBM_TDB
27	9	"9702596"	EPO; JPO; DERWENT; IBM_TDB
28	1	("6262513").PN.	US-PGPUB; USPAT; USOCR
29	166	onozawa.in.	US-PGPUB; USPAT; USOCR
30	111523	SAW	US-PGPUB; USPAT; USOCR
31	12 .	S29 and S30	US-PGPUB; USPAT; USOCR
32	5 ·	"2004032321"	EPO; JPO; DERWENT; IBM_TDB
33	3	"2003298389"	EPO; JPO; DERWENT; IBM_TDB
34	8655	surface adj acoustic adj wave	US-PGPUB; USPAT; USOCR

	Hits	Search Text	DBs
35	2924449	resin or film or sheet	US-PGPUB; USPAT; USOCR
36	1123640	roll or roller	US-PGPUB; USPAT; USOCR
37	63	S34 and S35 with S36	US-PGPUB; USPAT; USOCR
38	590	S34 and S36	US-PGPUB; USPAT; USOCR
39	1354452	thermoplastic or plastic or thermoset\$4	US-PGPUB; USPAT; USOCR
40	313	S38 and (S35 or S39)	US-PGPUB; USPAT; USOCR
41	250	S40 not S37	US-PGPUB; USPAT; USOCR
42	81629	piezoelectric	US-PGPUB; USPAT; USOCR
43	1925308	dice\$1 or dicing or cut\$4	US-PGPUB; USPAT; USOCR
44	3102	(S34 or S42) and (S35 or S39) same S36 and S43	US-PGPUB; USPAT; USOCR
45	2359	(S34 or S42) and (S35 or S39) with S36 and S43	US-PGPUB; USPAT; USOCR
46	49	S34 and (S35 or S39) with S36 and S43	US-PGPUB; USPAT; USOCR
47	7	S46 not S37	US-PGPUB; USPAT; USOCR
48	26742	S42 adj (element or device)	US-PGPUB; USPAT; USOCR
49	270	S48 with (S35 or S39) and (S35 or S39) with S36 and S43	rUS-PGPUB; USPAT; USOCR
50	14498	surface adj acoustic	EPO; JPO; DERWENT; IBM_TDB
51	966342	roll or roller	EPO; JPO; DERWENT; IBM_TDB

	Hits	Search Text	DBs
52	13896	surface adj acoustic adj wave	EPO; JPO; DERWENT; IBM_TDB
53	966342	roll or roller	EPO; JPO; DERWENT; IBM_TDB
54	53	S52 and S53	EPO; JPO; DERWENT; IBM_TDB
55	10	S50 and S51 not S54	EPO; JPO; DERWENT; IBM_TDB
56	2000938	thermoplastic or plastic or thermoset\$4 or resin	EPO; JPO; DERWENT; IBM_TDB
57	2425716	film or sheet	EPO; JPO; DERWENT; IBM_TDB
58	63	S52 and S56 adj S57	EPO; JPO; DERWENT; IBM_TDB
59	3	"2001053577"	EPO; JPO; DERWENT; IBM_TDB
60	3	"2001110946"	EPO; JPO; DERWENT; IBM_TDB
61	1381894	electronic or chip	EPO; JPO; DERWENT; IBM_TDB
62	390	S61 and S56 adj S57 and S53	EPO; JPO; DERWENT; IBM_TDB
63	994855	dice\$1 or dicing or cut\$4	EPO; JPO; DERWENT; IBM_TDB
64	62	S62 and S63	EPO; JPO; DERWENT; IBM_TDB
65	328	S62 not S64	EPO; JPO; DERWENT; IBM_TDB
66	3511	S52 and (S56 or S57)	EPO; JPO; DERWENT; IBM_TDB
67	1873163	board or substrate	EPO; JPO; DERWENT; IBM_TDB
68	2597	S66 and S67	EPO; JPO; DERWENT; IBM_TDB

	Hits	Search Text	DBs
69	279	1200 8110 203	EPO; JPO; DERWENT; IBM_TDB
70	1193369	lelectronic or chin	US-PGPUB; USPAT; USOCR
71	1221119	board or substrate	US-PGPUB; USPAT; USOCR
72	1294	HESTILLACII CITTIOLOGO STIPPI OT TAVPIT	US-PGPUB; USPAT; USOCR
73	171538	(S39 or resin) adj (film or sheet or layer)	US-PGPUB; USPAT; USOCR
74	149	(S34 or S70) with S71 and (S34 or S70) with S73 and S73 with S36	
75	7081	(S34 or S70) with S71 and (S35 or S39) with S36	US-PGPUB; USPAT; USOCR
76	4360	S75 and S43	US-PGPUB; USPAT; USOCR
77	122479	"156"/\$7.ccls.	US-PGPUB; USPAT; USOCR
78	464	S76 and S77	US-PGPUB; USPAT; USOCR
79	17424	flip adj chip	ŲS-PGPUB; USPAT; USOCR
80	54	15/9 and 5/3 with 536	US-PGPUB; USPAT; USOCR
81	179550	encansiliary,	US-PGPUB; USPAT; USOCR
82	563	S79 and S81 and S36	US-PGPUB; USPAT; USOCR
83	50	S79 and S81 same S36	US-PGPUB; USPAT; USOCR
84	1	("6262513").PN.	US-PGPUB; USPAT; USOCR

	Hits	Search Text	DBs
85	20	("4364017"   "4734608"   "5010270"   "5243250").PN. OR ("6262513").URPN.	US-PGPUB; USPAT; USOCR
86	65	S34 and (package or encapsulat\$3) and roller	US-PGPUB; USPAT; USOCR
87	8655	surface adj acoustic adj wave	US-PGPUB; USPAT; USOCR
88	65	S88 and (package or encapsulat\$3) and roller	US-PGPUB; USPAT; USOCR
89	65	S88 and (package or encapsulat\$3) and roller	US-PGPUB; USPAT; USOCR
90	2	"2004253839"	EPO; JPO; DERWENT; IBM_TDB
91	9	"9702596"	EPO; JPO; DERWENT; IBM_TDB
92	2	"02186662"	EPO; JPO; DERWENT; IBM_TDB
93	2	"2001176995"	EPO; JPO; DERWENT; IBM TDB
94	5	"2004032321"	EPO; JPO; DERWENT; IBM_TDB
95	2	"2002184884"	EPO; JPO; DERWENT; IBM_TDB
96	2038	SAW adj (chip or device)	EPO; JPO; DERWENT; IBM_TDB
97	9526	flip adj chip	EPO; JPO; DERWENT; IBM_TDB
98	966342	roll or roller	EPO; JPO; DERWENT; IBM_TDB
99	3901420	thermoplastic or plastic or thermoset\$4 or resin or sheet or film	EPO; JPO; DERWENT; IBM_TDB
100	11	S97 and (S98 or S100) and S99	EPO; JPO; DERWENT; IBM_TDB

	Hits	Search Text	DBs
101	85	S97 and S99	EPO; JPO; DERWENT; IBM_TDB
102	74	S102 not S101	EPO; JPO; DERWENT; IBM_TDB
103	536	S97 and (S98 or S100)	EPO; JPO; DERWENT; IBM_TDB
104	2841301	heat\$3 or soften\$3 or melt\$3	EPO; JPO; DERWENT; IBM_TDB
105	69	S104 and S105	EPO; JPO; DERWENT; IBM_TDB
106	1346545	seal\$3	US-PGPUB; USPAT; USOCR
107	756615	roller	US-PGPUB; USPAT; USOCR
108	16	S88 and S107 with S108	US-PGPUB; USPAT; USOCR
109	24	S88 and S107 same S108	US-PGPUB; USPAT; USOCR
110	8	S110 not S109	US-PGPUB; USPAT; USOCR
111	2626009	sheet or film	US-PGPUB; USPAT; USOCR
112	1465280	seal\$3 or encapsulant or encapsulat\$3	US-PGPUB; USPAT; USOCR
113	497765	"156"/\$7.ccls. or "310"/\$7.ccls. or "257"/\$7.ccls. or "438"/\$7.ccls. or "174"/\$7.ccls.	US-PGPUB; USPAT; USOCR
114	1604	S112 with S108 same S113 and S114	US-PGPUB; USPAT; USOCR
115	742	S112 with S108 with S113 and S114	US-PGPUB; USPAT; USOCR
116	1076062	electronic or S88 or SAW or piezoelectric	US-PGPUB; USPAT; USOCR

	Hits	Search Text	DBs
117	1221119	board or substrate	US-PGPUB; USPAT; USOCR
118	521	S115 and (S117 or S118)	US-PGPUB; USPAT; USOCR
119	1	("6262513").PN.	US-PGPUB; USPAT; USOCR
120	1	("4170811").PN.	EPO; JPO; DERWENT
121	2	"05055303"	EPO; JPO; DERWENT; IBM_TDB
122	13896	surface adj acoustic adj wave	EPO; JPO; DERWENT; IBM_TDB
123	4	(S97 or S123) and S100 and rolling	EPO; JPO; DERWENT; IBM_TDB
124	5	(S97 or S123) and S100 and (rolled or rolling)	EPO; JPO; DERWENT; IBM_TDB
125	3529	S112 with S113 with S108	US-PGPUB; USPAT; USOCR
126	64	S126 and S117 with S118	US-PGPUB; USPAT; USOCR
127	422789	chip	US-PGPUB; USPAT; USOCR
128	1725772	thermoplastic or plastic or thermoset\$4 or resin	US-PGPUB; USPAT; USOCR
129	526	S128 with S118 and S129 with S108	US-PGPUB; USPAT; USOCR
130	1109	S128 with S118 and S129 same S108	US-PGPUB; USPAT; USOCR
131	913	S131 and (S113 or packag\$3 or protect\$3)	US-PGPUB; USPAT; USOCR
132	475	S132 not S130	US-PGPUB; USPAT; USOCR
133	61345	inkjet or ink adj jet or printhead	US-PGPUB; USPAT; USOCR

	Hits	Search Text	DBs
134	351	S133 not S134	US-PGPUB; USPAT; USOCR
135	1087	310/313R.ccls.	US-PGPUB; USPAT; USOCR
136	756843	roller	US-PGPUB; USPAT; USOCR
137	5	S136 and S137	US-PGPUB; USPAT; USOCR
138	980	310/340,348.ccls.	US-PGPUB; USPAT; USOCR
139	12	S137 and S139	US-PGPUB; USPAT; USOCR
140	693	310/311.ccls.	US-PGPUB; USPAT; USOCR
141	18	S137 and S141	US-PGPUB; USPAT; USOCR
142	448044	rolled or rolling	US-PGPUB; USPAT; USOCR
143	51	S143 and (S136 or S139 or S141)	US-PGPUB; USPAT; USOCR
144	1	("6262513").PN.	US-PGPUB; USPAT; USOCR